IGBT - Field Stop 600 V, 20 A

FGH20N60UFD

Description

Using novel field stop IGBT Technology, ON Semiconductor's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.

Features

- High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.8 \text{ V}$ @ $I_C = 20 \text{ A}$
- High Input Impedance
- Fast Switching
- This Device is Pb-Free and is RoHS Compliant

Applications

• Solar Inverter, UPS, Welder, PFC

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector to Emitter Voltage	V _{CES}	600	V
Gate to Emitter Voltage	V_{GES}	±20	V
Transient Gate to Emitter Voltage		±30	
Collector Current @ Tc = 25°C @ Tc = 100°C	Ic	40 20	Α
Pulsed Collector Current @ Tc = 25°C	I _{CM} (Note 1)	60	Α
Diode Forward Current @ Tc = 25°C @ Tc = 100°C	I _F	20 10	Α
Pulsed Diode Maximum Forward Current	I _{FM} (Note 1)	60	Α
Maximum Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	165 66	W
Operating Junction Temperature	T_J	-55 to + 150	°C
Storage Temperature Range	T _{stg}	-55 to + 150	°C
Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	T _L	300	°C

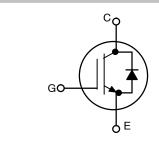
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

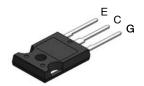
1. Repetitive rating: Pulse width limited by max. junction temperature.



ON Semiconductor®

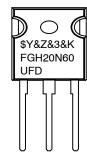
www.onsemi.com





TO-247-3LD CASE 340CK

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

FGH20N60UFD = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

THERMAL CHARACTERISTICS

Parameter	Symbol	Тур.	Max.	Unit
Thermal Resistance Junction-to-Case, for IGBT	$R_{ heta JC}$	-	0.76	°C/W
Thermal Resistance Junction-to-Case, for Diode	$R_{ heta JC}$	-	2.51	°C/W
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	_	40	°C/W

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH20N60UFDTU	FGH20N60UFD	TO-247	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_C = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector to Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0 V, I _C = 250 μA	600	_	-	V
Temperature Coefficient of Breakdown Voltage	$\Delta BV_{CES}/\Delta T_{J}$	$V_{GE} = 0 \text{ V, } I_{C} = 250 \mu\text{A}$	-	0.6	_	V/°C
Collector Cut-Off Current	I _{CES}	V _{CE} = V _{CES} , V _{GE} = 0 V	-	-	250	μΑ
G-E Leakage Current	I _{GES}	V _{GE} = V _{GES} , V _{CE} = 0 V	-	-	±400	nA
ON CHARACTERISTICs						
G-E Threshold Voltage	V _{GE(th)}	$I_C = 250 \mu A, V_{CE} = V_{GE}$	4.0	5.0	6.5	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	I _C = 20 A, V _{GE} = 15 V	-	1.8	2.4	V
		I _C = 20 A, V _{GE} = 15 V, T _C = 125°C	-	2.0	-	V
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ies}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	940	-	pF
Output Capacitance	C _{oes}	1	-	110	-	pF
Reverse Transfer Capacitance	C _{res}	1	-	40	_	pF
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(on)}	V _{CC} = 400 V, I _C = 20 A,	-	13	-	ns
Rise Time	t _r	$R_G = 10 \Omega$, $V_{GE} = 15 V$, Inductive Load, $T_C = 25^{\circ}C$	-	17	-	ns
Turn-Off Delay Time	t _{d(off)}		-	87	-	ns
Fall Time	t _f		-	32	64	ns
Turn-On Switching Loss	E _{on}	1	-	0.38	_	mJ
Turn-Off Switching Loss	E _{off}	1	-	0.26	-	mJ
Total Switching Loss	E _{ts}	1	-	0.64	-	mJ
Turn-On Delay Time	t _{d(on)}	V _{CC} = 400 V, I _C = 20 A,	-	13	-	ns
Rise Time	t _r	$R_G = 10 \Omega$, $V_{GE} = 15 V$, Inductive Load, $T_C = 125^{\circ}C$	-	16	-	ns
Turn-Off Delay Time	t _{d(off)}		-	92	-	ns
Fall Time	t _f		-	63	-	ns
Turn-On Switching Loss	E _{on}		-	0.41	-	mJ
Turn-Off Switching Loss	E _{off}		-	0.36	-	mJ
Total Switching Loss	E _{ts}		-	0.77	-	mJ
Total Gate Charge	Qg	V _{CE} = 400 V, I _C = 20 A, V _{GE} = 15 V	-	63	-	nC
Gate to Emitter Charge	Q _{ge}	1	-	7	-	nC
Gate to Collector Charge	Q _{gc}	1	-	32	-	nC

ELECTRICAL CHARACTERISTICS OF THE DIODE ($T_J = 25^{\circ}C$ unless otherwise noted)

Parametr	Symbol	Test Conditions		Min	Тур	Max	Unit
Diode Forward Voltage	V_{FM}	I _F = 10 A	T _C = 25°C	_	1.9	2.5	V
			T _C = 125°C	_	1.7	_	
Diode Reverse Recovery Time	t _{rr}	$I_F = 10 \text{ A, } di_F/dt = 200 \text{ A/}\mu\text{s}$	T _C = 25°C	_	34	_	ns
			T _C = 125°C	_	57	_	
Diode Reverse Recovery Charge	Q _{rr}		T _C = 25°C	_	41	_	nC
			T _C = 125°C	_	96	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

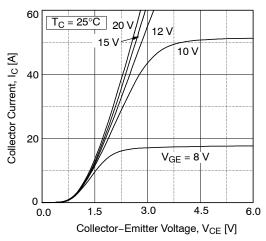
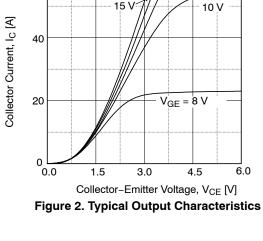


Figure 1. Typical Output Characteristics



20

12 V

T_C = 125°C

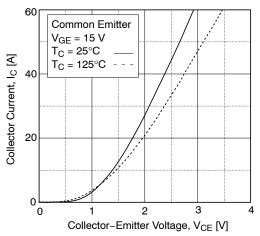


Figure 3. Typical Saturation Voltage Characteristics

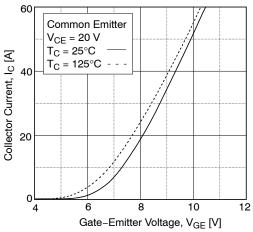


Figure 4. Transfer Characteristics

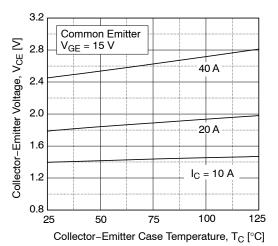


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

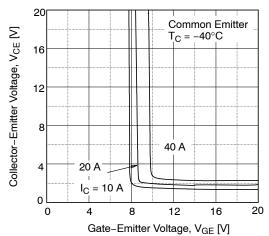


Figure 6. Saturation Voltage vs. V_{GE}

TYPICAL CHARACTERISTICS

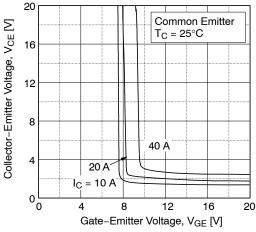


Figure 7. Saturation Voltage vs. V_{GE}

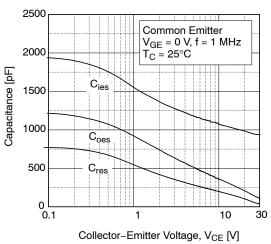
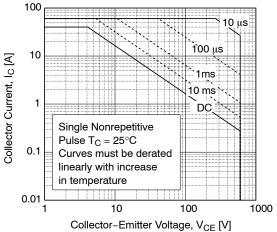


Figure 9. Capacitance Characteristics



Collector-Emitter Voltage, V_{CE} [V] Figure 11. SOA Characteristics

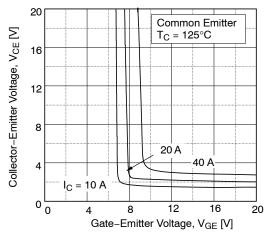


Figure 8. Saturation Voltage vs. V_{GE}

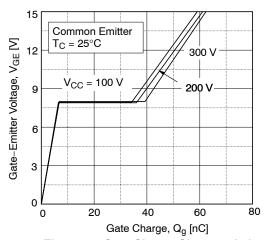


Figure 10. Gate Charge Characteristics

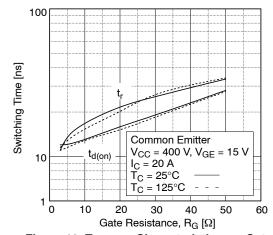


Figure 12. Turn-on Characteristics vs. Gate Resistance

TYPICAL CHARACTERISTICS

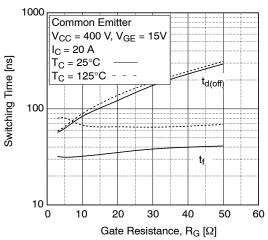


Figure 13. Turn-off Characteristics vs. Gate Resistance

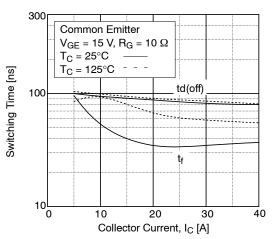


Figure 15. Turn-off Characteristics vs.
Collector Current

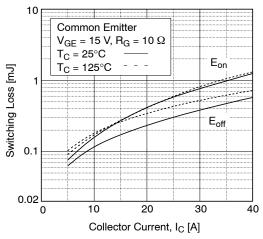


Figure 17. Switching Loss vs. Collector Current

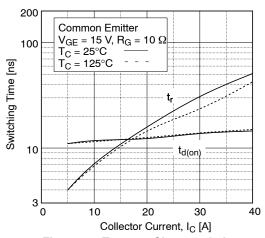


Figure 14. Turn-on Characteristics vs. Collector Current

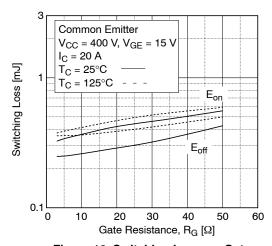


Figure 16. Switching Loss vs. Gate Resistance

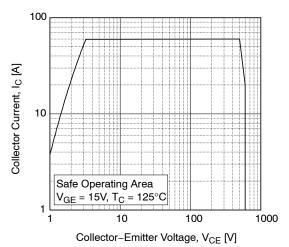


Figure 18. Turn-off Switching SOA Characteristics

TYPICAL CHARACTERISTICS

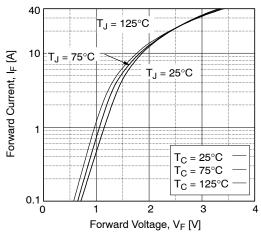


Figure 19. Forward Characteristics

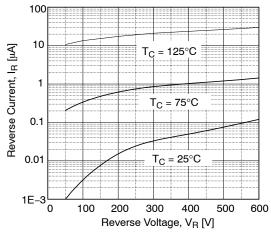


Figure 20. Reverse Current

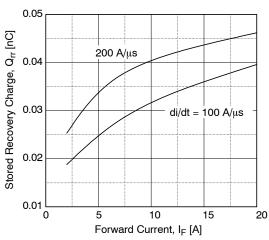


Figure 21. Stored Charge

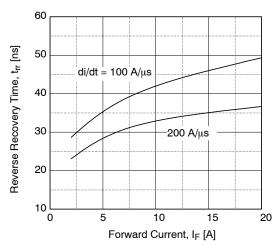


Figure 22. Reverse Recovery Time

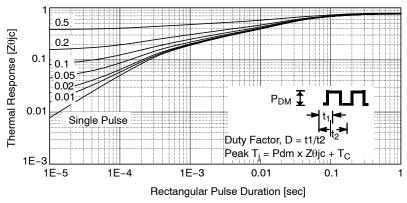


Figure 23. Transient Thermal Impedance of IGBT

TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

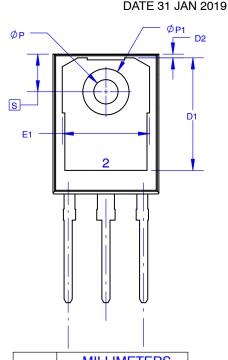
A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS				
DIIVI	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E	15.37	15.62	15.87		
E1	12.81	~	~		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Ø P1	6.60	6.80	7.00		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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DESCRIPTION:	TO-247-3LD SHORT LEAD		PAGE 1 OF 1	

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